
M16C/63 GroupPower Control
Low Current Consumption Setting

R01AN0332EJ0102

Rev. 1.02

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1. Abstract

This application note describes the setting method for low current consumption in the M16C/63 Group.

2. Introduction

The application example described in this document applies to the following microcomputer (MCU):

- MCU: M16C/63 Group

This application note can be used with other M16C Family MCUs which have the same special function registers (SFRs) as the above group. Check the user's manual for any modifications to functions. Careful evaluation is recommended before using the program described in this application note.

3. Outline

The amount of current consumption correlates with the number of operating clocks and frequency. If there are fewer operating clocks and a lower frequency, current consumption will be low.

Sub clock division and f1 provide disabled function are added for the low consumption system in the M16C/63 Group.

This section introduces a method to reduce current consumption.

3.1 Clock Operating Modes

3.1.1 Normal Operating Mode

In normal operating mode, the CPU clock and the peripheral function clocks are both supplied, thus the CPU and the peripheral functions are operating. Power control is exercised by controlling the CPU clock frequency. The higher the CPU clock frequency, the higher the processing capability. The lower the CPU clock frequency, the lower the power consumption in the chip. If unnecessary oscillators are stopped, current consumption is further reduced.

3.1.2 Wait Mode

In wait mode, the CPU clock stops, then the CPU, watchdog timer, and $\overline{\text{NMI}}/\overline{\text{SD}}$ digital filter also stop as they are operated by the CPU clock. However, if the CSPRO bit in the CSPR register is 1 (count source protection enabled), the watchdog timer remains active. Since the clock oscillator does not stop, peripheral functions which are provided peripheral function clocks keep operating.

Peripheral Function Clock Stop Function:

When the CM02 bit in the CM0 register is 1 (peripheral function clock f1 stops in wait mode), the f1 clock stops while in wait mode, then current consumption is reduced. With the exception of f1, peripheral clocks (i.e. fOCO40M, fOCO-F, fOCO-S, fC, and fC32) are not stopped by the CM02 bit.

3.1.3 Stop Mode

In stop mode, all oscillators stop. Therefore the CPU clock and peripheral function clocks stop, then the CPU and peripheral functions using these clocks stop operating. The least amount of current is consumed in this mode. If the voltage applied to pins VCC1 and VCC2 is VRAM or greater, the contents of the internal RAM are retained. When applying 1.8 V or less to pins VCC1 and VCC2, make sure $VCC1 \geq VCC2 \geq VRAM$.

The peripheral functions activated by external signals keep operating.

3.2 Power Control in Flash Memory

3.2.1 Stopping Flash Memory

When the flash memory is stopped, current consumption is reduced. While the flash memory is stopped, execute a program in any area other than the flash memory. Figure 3.1 shows the Stopping and Restarting the Flash Memory.

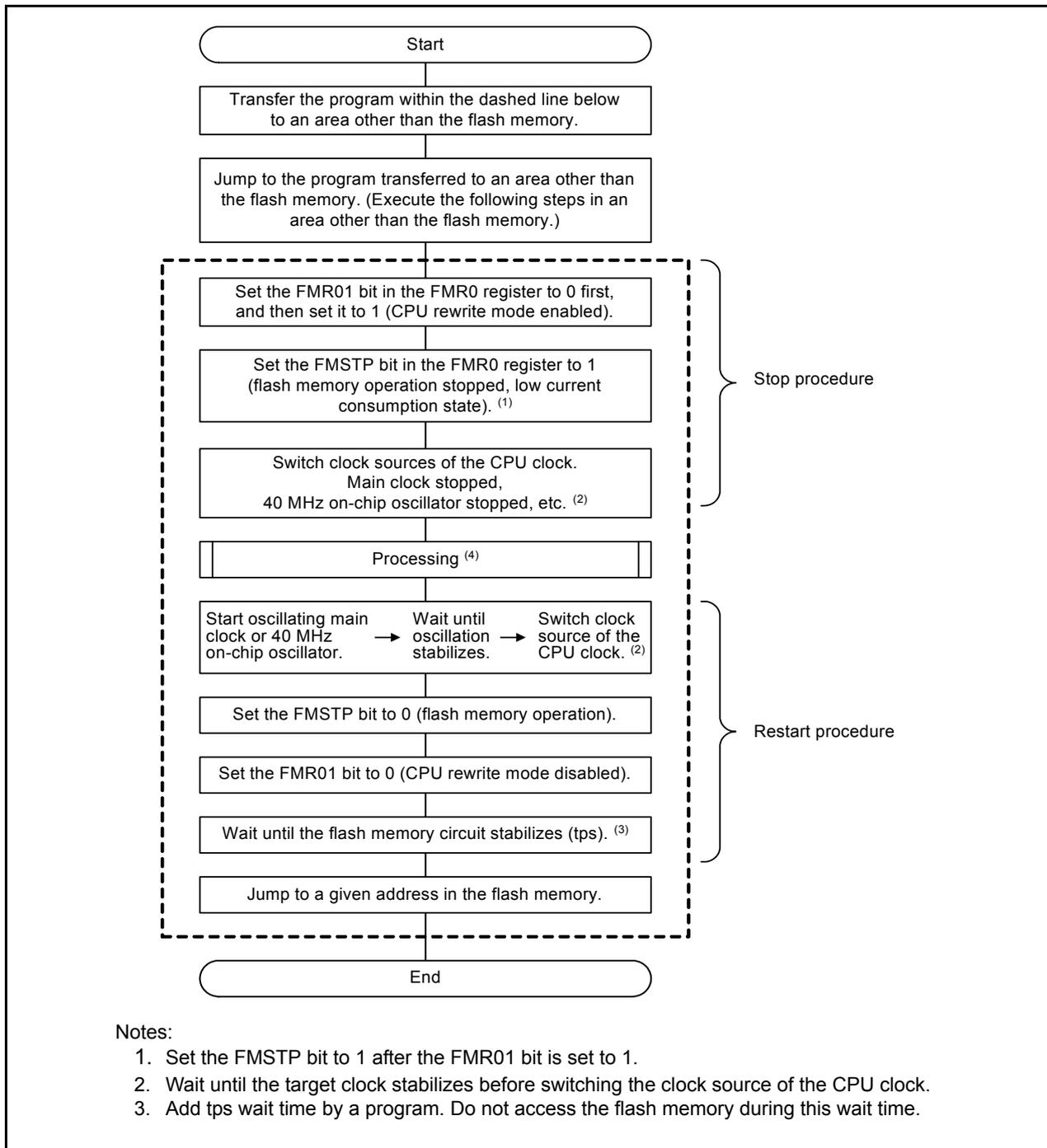


Figure 3.1 Stopping and Restarting the Flash Memory

3.2.2 Reading the Flash Memory

Current consumption while reading the flash memory can be reduced by setting bits FMR22 and FMR23 in the FMR2 register.

3.2.2.1 Slow Read Mode

Slow read mode can be used when $f(\text{BCLK})$ is slower than or equal to $f(\text{SLOW_R})$ and the PM17 bit in the PM1 register is 1 (1 wait). When the sub clock or 125 kHz on-chip oscillator clock is used as the clock source of the CPU clock, a wait is not necessary.

(Technical update number: TN-16C-A179A/E).

Figure 3.2 shows Setting and Canceling Slow Read Mode.

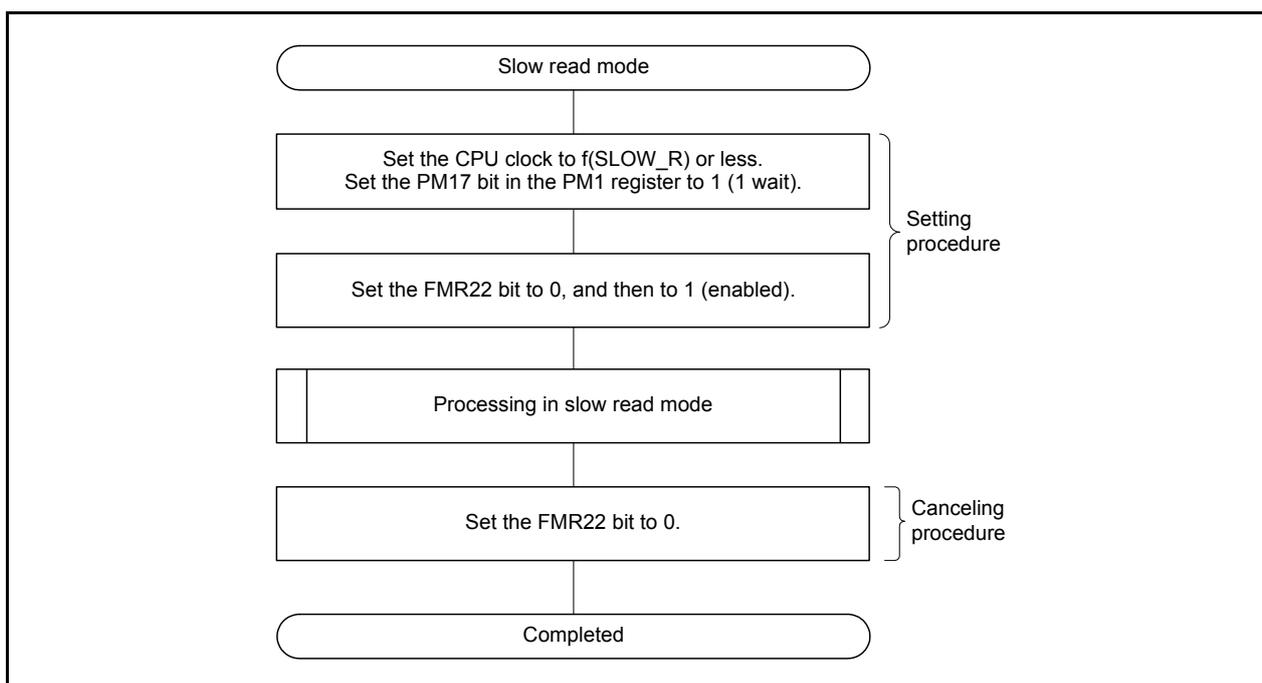


Figure 3.2 Setting and Canceling Slow Read Mode

Do not set the FMR22 bit in the FMR2 register to 1 (slow read mode enabled) when the FMR01 bit in the FMR0 register is 1 (CPU rewrite mode enabled).

3.2.2.2 Low Current Consumption Read Mode

Low current consumption read mode can be used when the CM07 bit in the CM0 register is 1 (sub clock used as CPU clock). Figure 3.3 shows Setting and Canceling Low Current Consumption Read Mode.

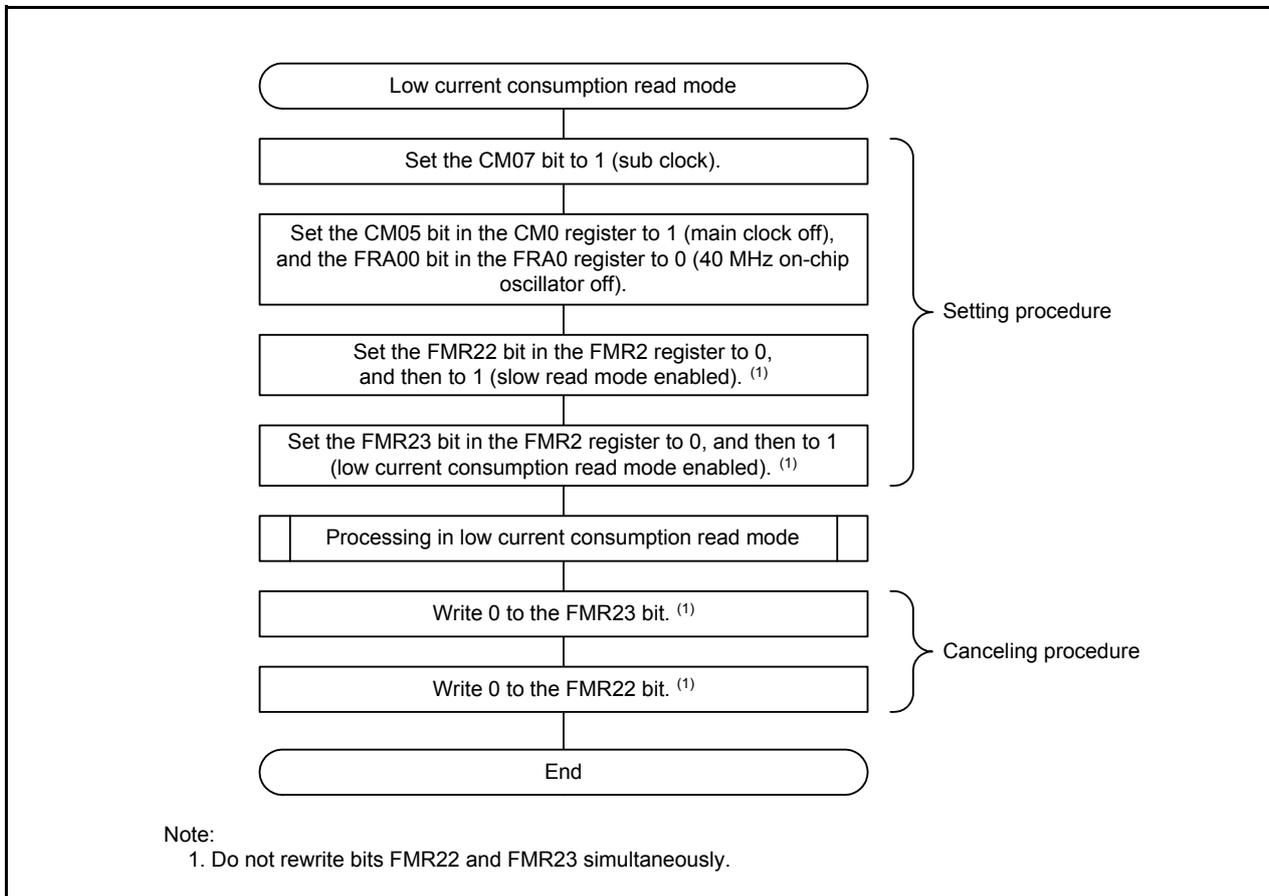


Figure 3.3 Setting and Canceling Low Current Consumption Read Mode

Do not enter wait mode from low current consumption read mode. To enter wait mode from this mode, set the FMR23 bit in the FMR2 register to 0 (low current consumption read mode disabled).

Do not enter wait mode from CPU rewrite mode. To enter wait mode from this mode, set the FMR01 bit in the FMR0 register to 0 (CPU rewrite mode disabled), and disable DMA transfer.

Do not enter stop mode from low current consumption read mode. To enter stop mode from this mode, set the FMR23 bit in the FMR2 register to 0 (low current consumption read mode disabled).

Do not enter stop mode from CPU rewrite mode. To enter stop mode from this mode, set the FMR01 bit in the FMR0 register to 0 (CPU rewrite mode disabled), and disable DMA transfer.

Enter low current consumption read mode through slow read mode.

When the FMR23 bit in the FMR2 register is 1 (low current consumption read mode enabled), do not set the FMSTP bit to 1 (flash memory stopped). Also, when the FMSTP bit is 1, do not set the FMR23 bit to 1. When the FMR01 bit in the FMR0 register to 1 (CPU rewrite mode enabled), do not set the FMR23 bit in the FMR2 register to 1 (low current consumption read mode enabled).

3.3 Reducing Current Consumption

To reduce current consumption, refer to the descriptions below when designing a system or writing a program.

3.3.1 Ports

The MCU retains the state of each I/O port even when it enters wait mode or stop mode. A current flows in the active output ports. A shoot-through current flows to the input ports in the high-impedance state. When entering wait mode or stop mode, first set unused ports to input and stabilize the potential.

3.3.2 A/D Converter

When not performing A/D conversion, set the PUMPON bit in the ADCON1 register to 0 (voltage multiplier off) and the ADSTBY bit in the ADCON1 register to 0 (A/D operation stop). Also, before entering wait mode or stop mode, fix analog pins to the stabilized potential.

3.3.3 D/A Converter

When not performing D/A conversion, set the DAiE bit in the DACON register to 0 (output disabled) and the DAi register to 00h (i = 0, 1).

3.3.4 Stopping Peripheral Functions

Use the PCLKSTP1 register to disable providing f1 to the peripheral functions not using f1.
Use the CM02 bit in the CM0 register to stop unnecessary peripheral functions while in wait mode.

3.3.5 Switching the Oscillation-Driving Capacity

Set the driving capacity to low when oscillation is stable.

4. Application Example

4.1 Settings in the Sample Code

The sample code configures the settings below from the settings for low current consumption described in 3. Outline.

Table 4.1 lists the Settings of Sample Code.

Table 4.1 Settings of Sample Code

Item		When in Low Current Consumption Mode	When in Normal Operating Mode
Program location		RAM	ROM
Clocks	CPU clock	Sub clock divided-by-2	Main clock (no division) (low drive capacity)
	Main clock	Stopped	Oscillating
	125 kHz on-chip oscillator		Stopped (oscillating only after reset)
	40 MHz on-chip oscillator		Stopped
	Sub clock	Oscillating	Oscillating
Peripheral clocks (real-time clock, timers, UART, remote control signal receiver, A/D converter, SIO, pulse width modulator, multi-master I ² C)		f1 provision disabled	
Flash memory operation		Stopped	Operating

Settings for the other peripheral functions are as follows:

- A/D converter: A/D operation stopped, voltage multiplier off
- D/A converter: D/A0 output disabled, D/A1 output disabled
- Unused ports: Input mode (pull-down ⁽¹⁾)

Note:

1. Pull-down is performed externally in the sample code.

4.2 Sample Code Operation

The following shows the sample code operation.

- (1) Initialize the CPU and peripheral functions.
- (2) Wait until the $\overline{\text{INT0}}$ interrupt occurs.
- (3) Transfer the program used in the RAM.
- (4) Set the start address of the relocatable vector table for the RAM in the INTB register.
- (5) Jump to the RAM, and execute the program.
 - (5)-1 Set the sub clock as the CPU clock divide-by-2.
 - (5)-2 Stop the main clock and on-chip oscillator.
 - (5)-3 Enable CPU rewrite mode.
 - (5)-4 Stop the flash memory, and set to low current consumption status.
 - (5)-5 Wait until the $\overline{\text{INT1}}$ interrupt occurs.
 - (5)-6 Enable flash memory operation. (1)
 - (5)-7 Disable CPU rewrite mode.
 - (5)-8 Wait until the flash memory circuit becomes stable.
 - (5)-9 Set the main clock (no division) as the CPU clock after the main clock oscillates.
- (6) Set the start address of relocatable vector table for the ROM in the INTB register, and return to (2).

Note:

1. When enabling flash memory operation (FMSTP bit is set to 0), wait for tps or longer after the flash memory stops (FMSTP bit is set to 1).

tps: Wait time until the flash memory circuit stabilizes.

Figure 4.1 shows the Operation Outline.

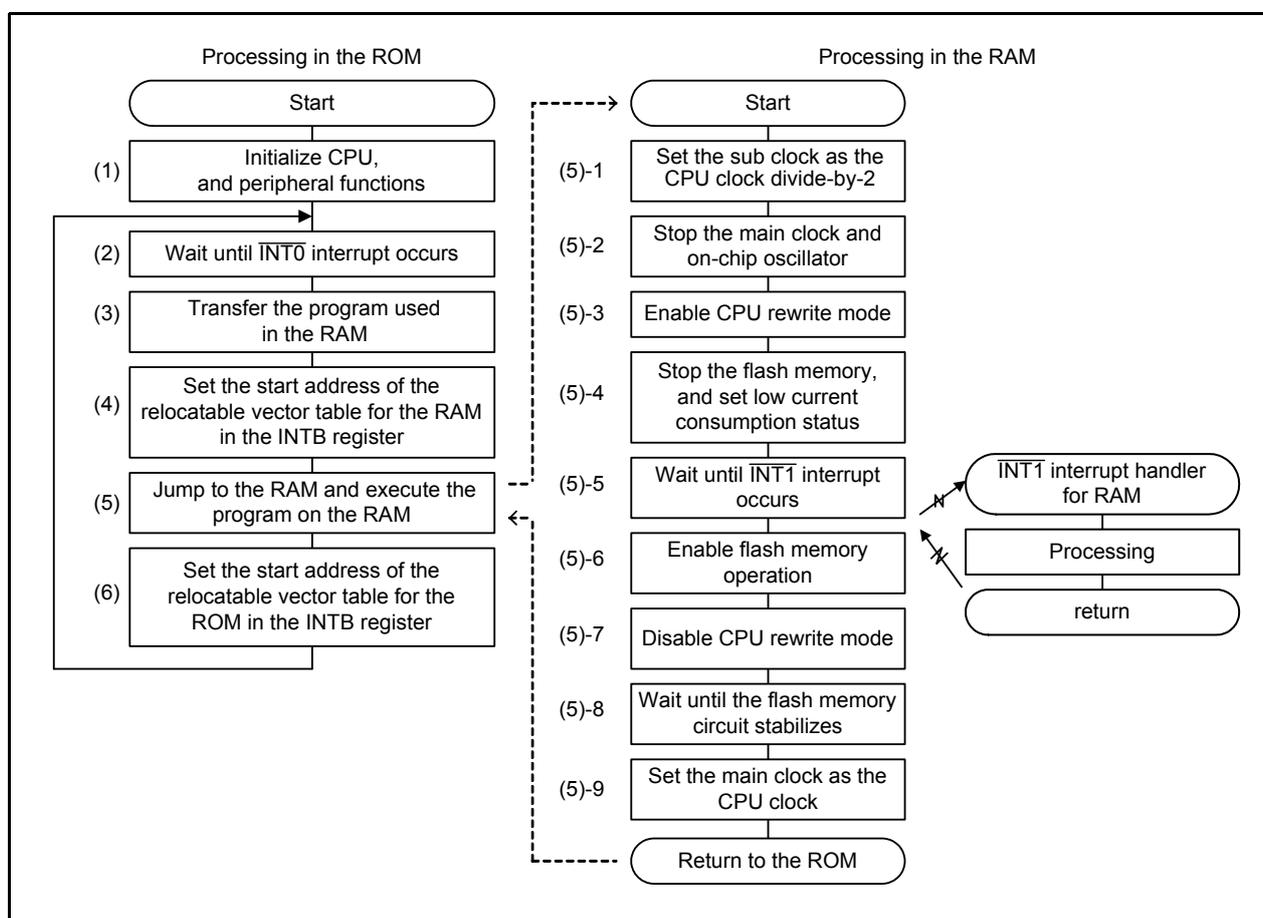


Figure 4.1 Operation Outline

4.3 Function Tables

Declaration	void main(void)
Outline	Main function
Argument	None
Variable (global)	None
Returned value	None
Function	When the $\overline{\text{INT0}}$ interrupt occurs, the program written in the internal flash memory is transferred to the RAM. Then the transferred program on the RAM is executed.

Declaration	void mcu_init(void)
Outline	CPU initialization
Argument	None
Variable (global)	None
Returned value	None
Function	Set the main clock (no division) as the CPU clock.

Declaration	void peripheral_init(void)
Outline	Peripheral low current consumption setting
Argument	None
Variable (global)	None
Returned value	None
Function	Stop providing f1 to the peripheral functions not using f1. Set XIN-XOUT drive capacity to low, the sub clock to divided-by-2, and oscillate the sub clock. Set ports, the A/D converter and the D/A converter.

Declaration	void stopping_flash_memory(void)		
Outline	Flash memory stop/operate function		
Argument	None		
Variable (global)	Type	Variable name	Contents
	unsigned char	flg_wait_int1_int	For checking an $\overline{\text{INT1}}$ interrupt occurrence
Returned value	None		
Function	Enable CPU rewrite mode, disable the flash memory operation, and set the mode to low current consumption mode. Enable the flash memory operation after the $\overline{\text{INT1}}$ interrupt occurs.		

Declaration	void cpu_slow(void)
Outline	System clock slow function
Argument	None
Variable (global)	None
Returned value	None
Function	Set the sub clock as the CPU clock. Stop the main clock and on-chip oscillator.

Declaration	void cpu_fast(void)
Outline	System clock fast function
Argument	None
Variable (global)	None
Returned value	None
Function	Oscillate the main clock by setting the CM05 bit in the CM0 register. After the main clock oscillation has been confirmed by the CM23 bit in the CM2 register 10 times continuously, set the main clock (no division) as the CPU clock.

Declaration	void send_to_ram(void)
Outline	Send to RAM function
Argument	None
Variable (global)	None
Returned value	None
Function	Transfer the flash memory stop/operate function, system clock slow function, and system clock fast function to the RAM.

Declaration	void send_to_ram_vector(void)
Outline	Send to RAM vector function
Argument	None
Variable (global)	None
Returned value	None
Function	Transfer an interrupt handler used in the RAM.

Declaration	void renewal_of_ram_vector_t(void)
Outline	Renewal of RAM vector table function
Argument	None
Variable (global)	None
Returned value	None
Function	Create the relocatable vector table used in the RAM.

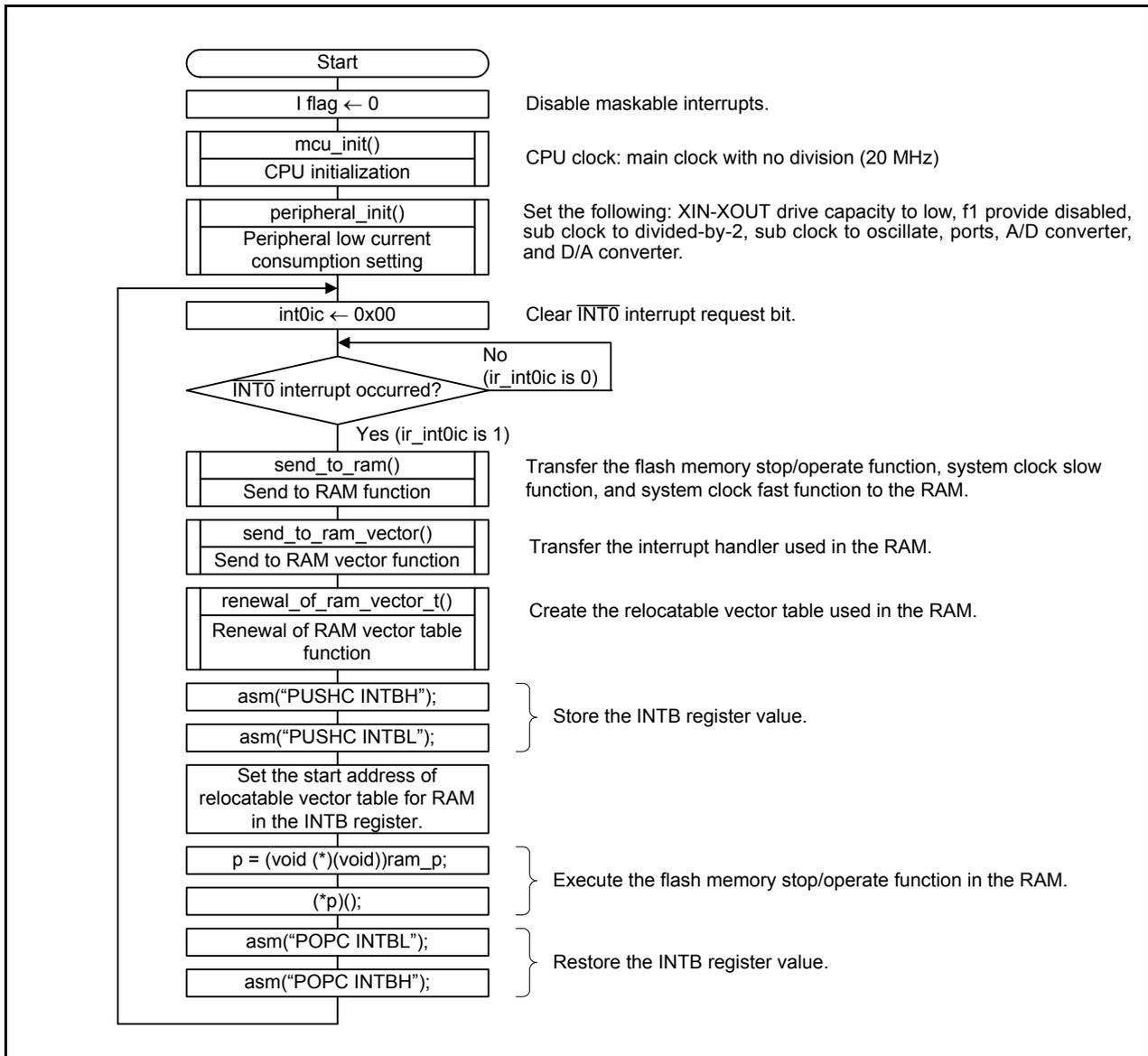
Declaration	void asm_smovf(void_far *_source, void_near *_dest, unsigned int _size)	
Outline	RAM transfer function	
Argument	Argument name	Meaning
	void_far *_source	Transferred source address (program)
	void_near *_dest	Transferred destination address (RAM area)
	unsigned int _size	Transfer size
Variable (global)	None	
Returned value	None	
Function	Transfer the specified area to the RAM area.	

Declaration	void ram_int_dummy(void)	
Outline	RAM interrupt dummy function	
Argument	None	
Variable (global)	None	
Returned value	None	
Function	Dummy function for the RAM. Add a processing if needed.	

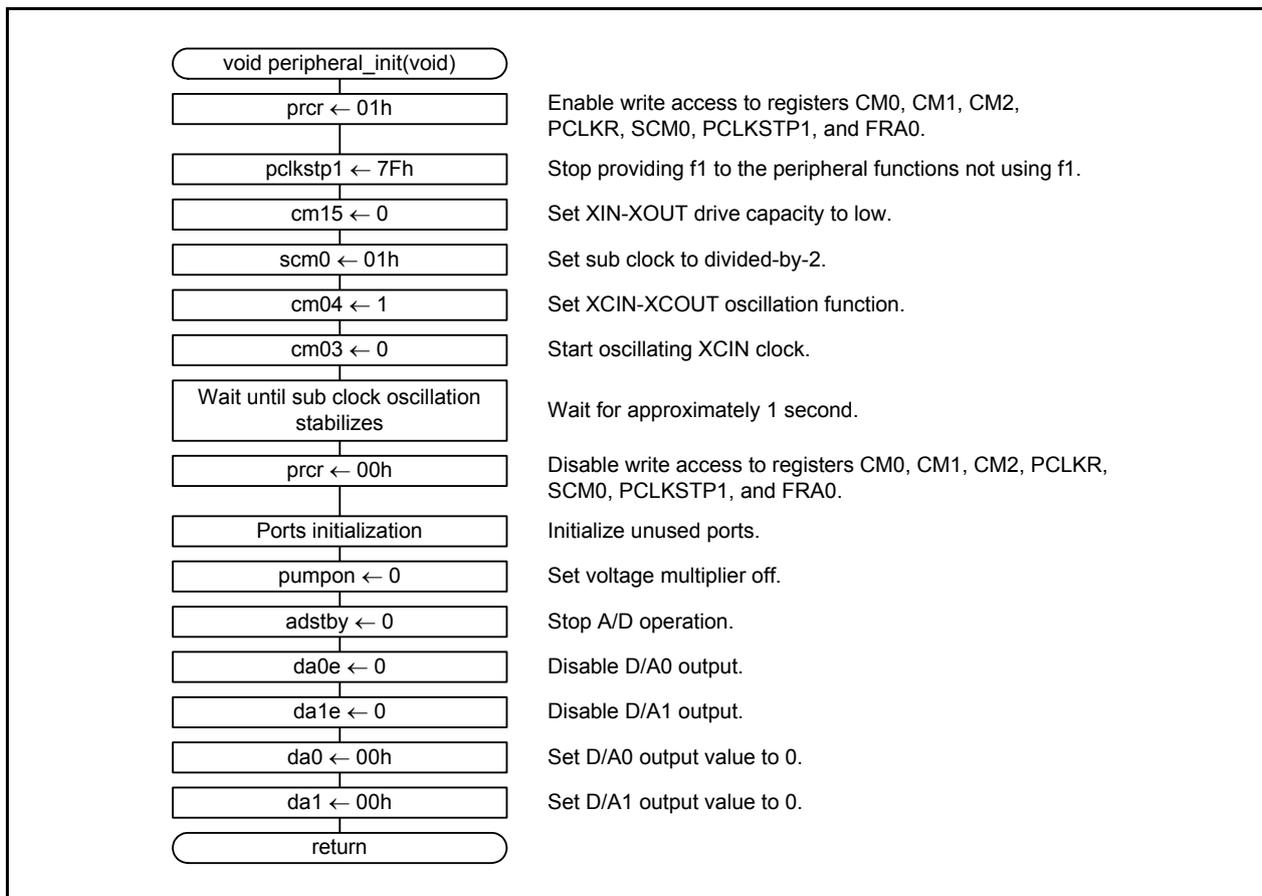
Declaration	void ram_int_int1(void)		
Outline	RAM $\overline{\text{INT1}}$ interrupt function		
Argument	None		
Variable (global)	Type	Variable name	Contents
	unsigned char	flg_wait_int1_int	For checking an $\overline{\text{INT1}}$ interrupt occurrence
Returned value	None		
Function	Invert port P0_0.		

4.4 Flowcharts

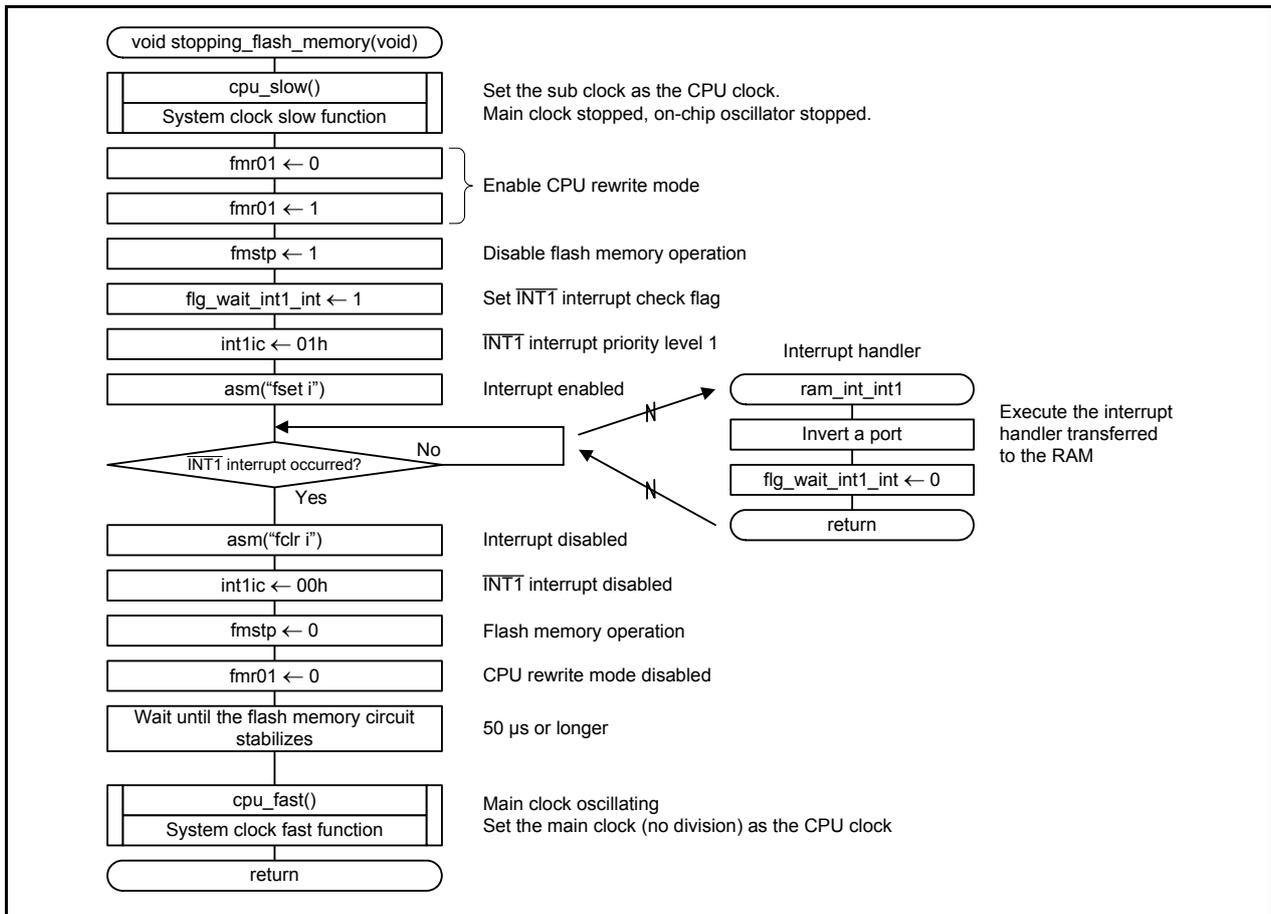
4.4.1 Main Processing



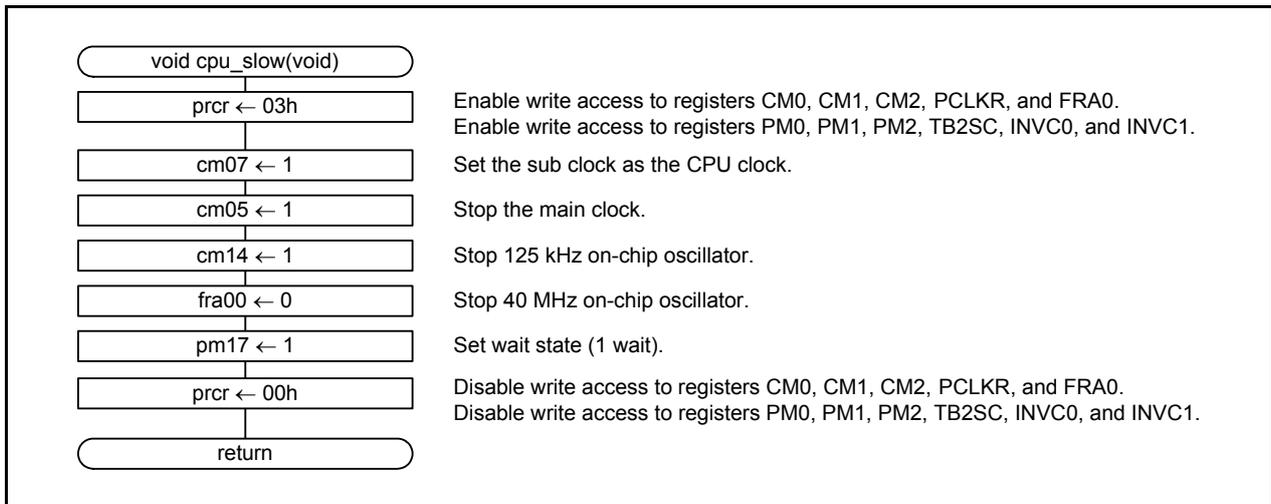
4.4.2 Peripheral Low Current Consumption Setting



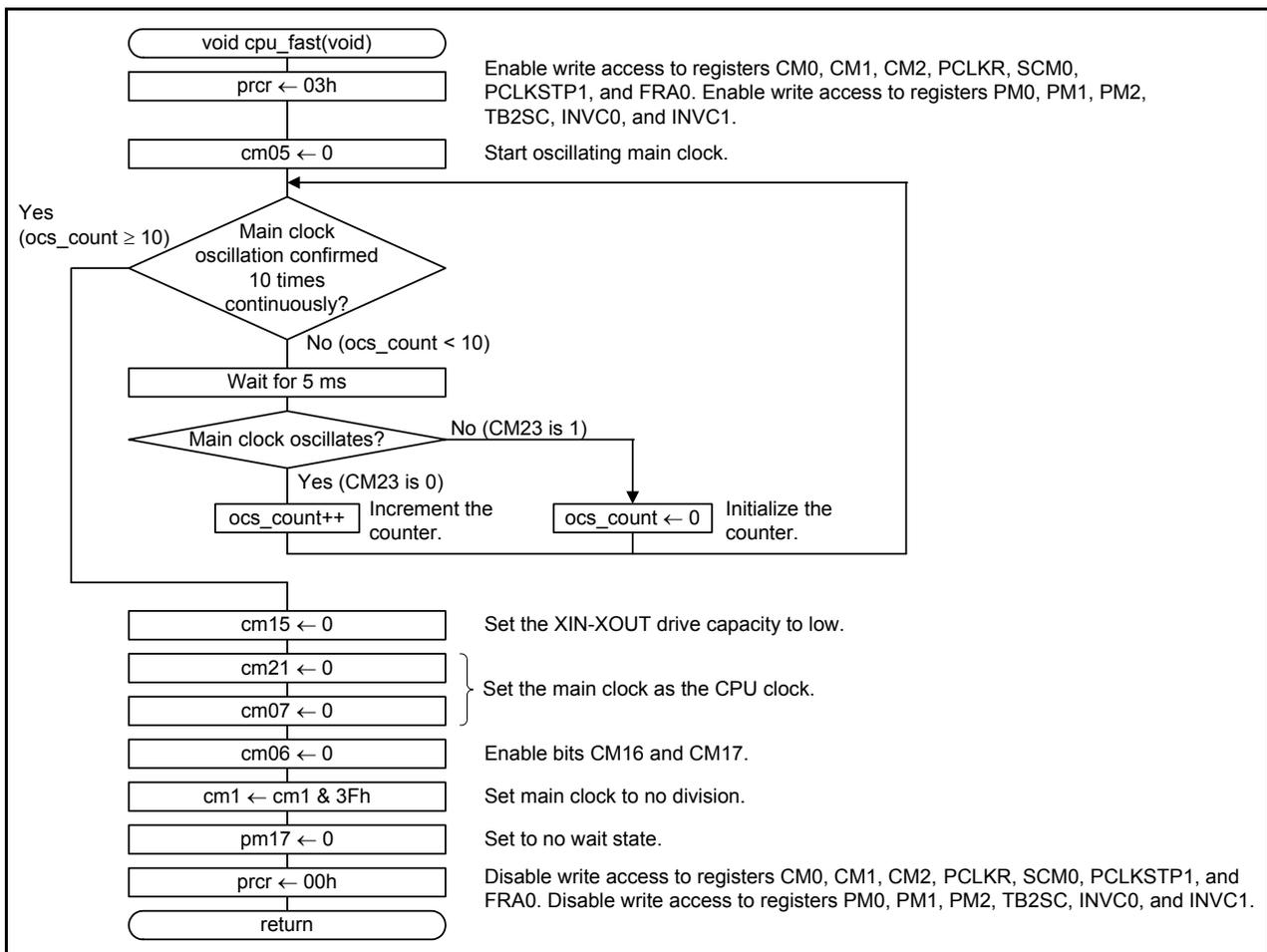
4.4.3 Flash Memory Stop/Operate Function



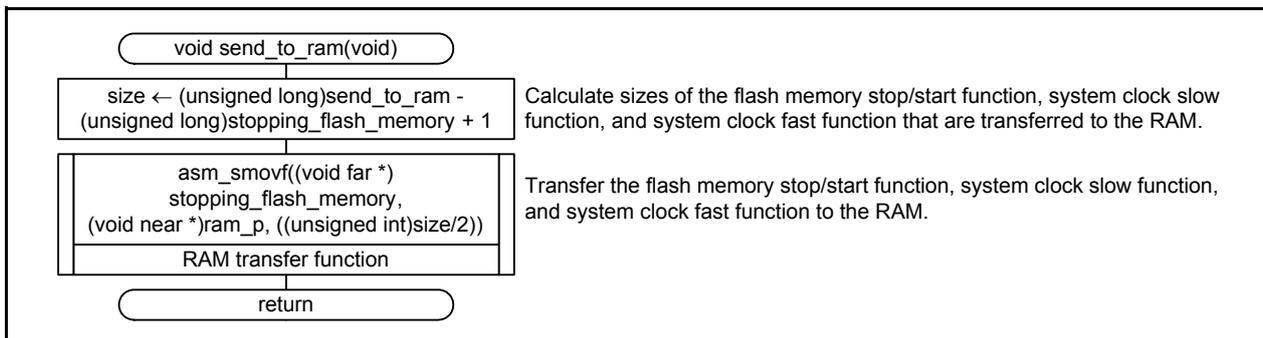
4.4.4 System Clock Slow Function



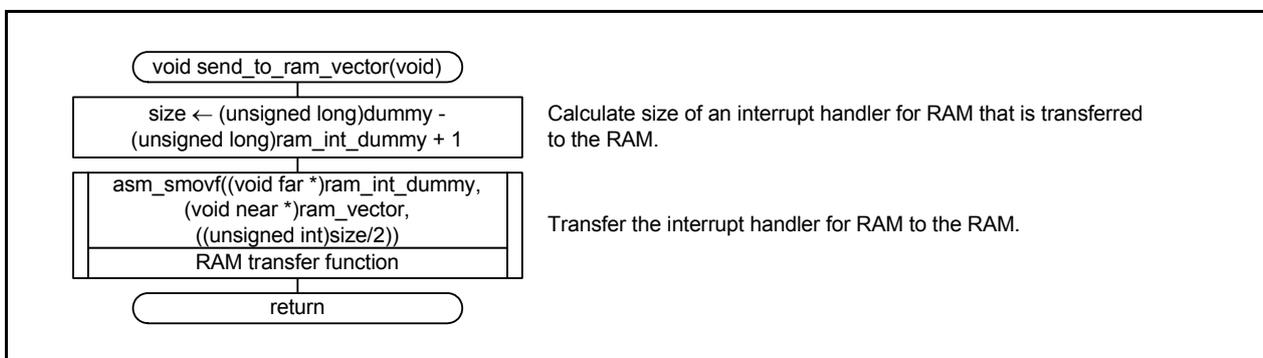
4.4.5 System Clock Fast Function



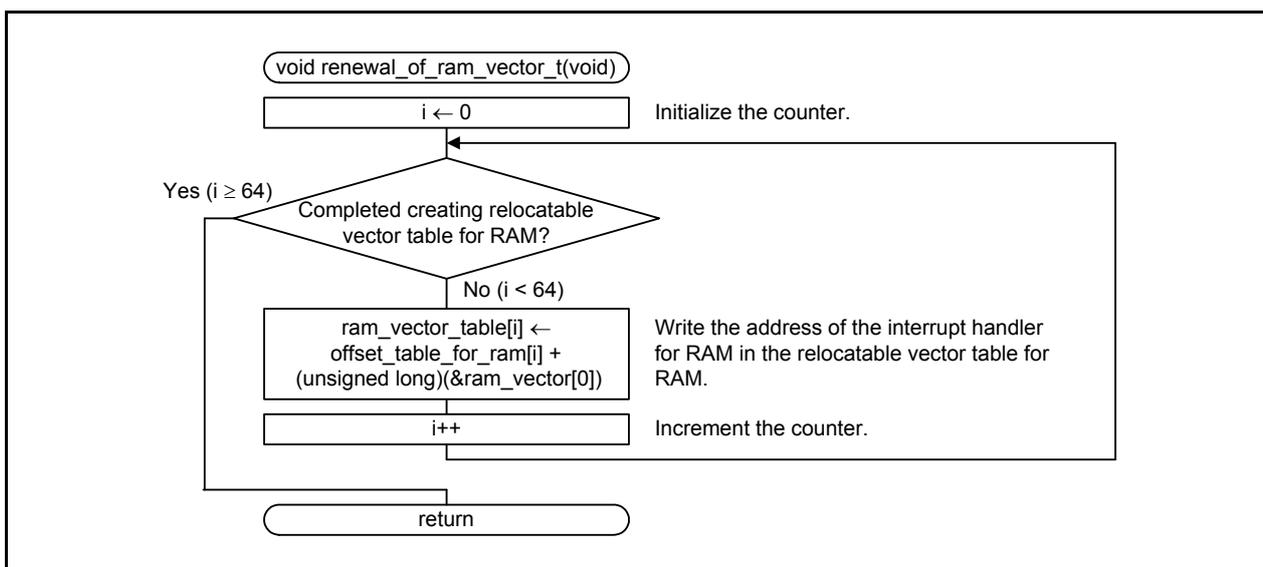
4.4.6 Send to RAM Function



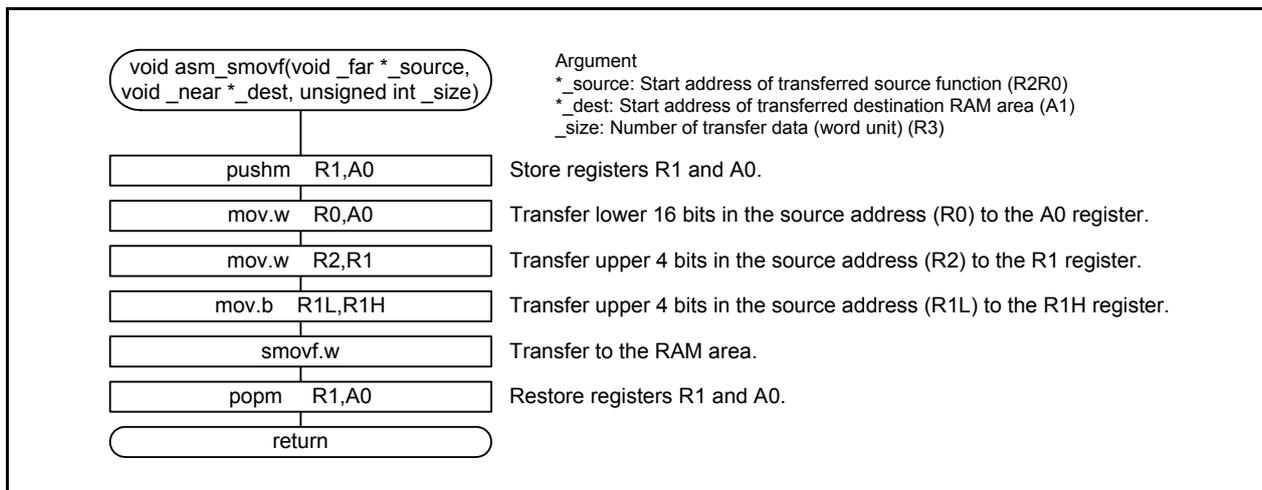
4.4.7 Send to RAM Vector Function



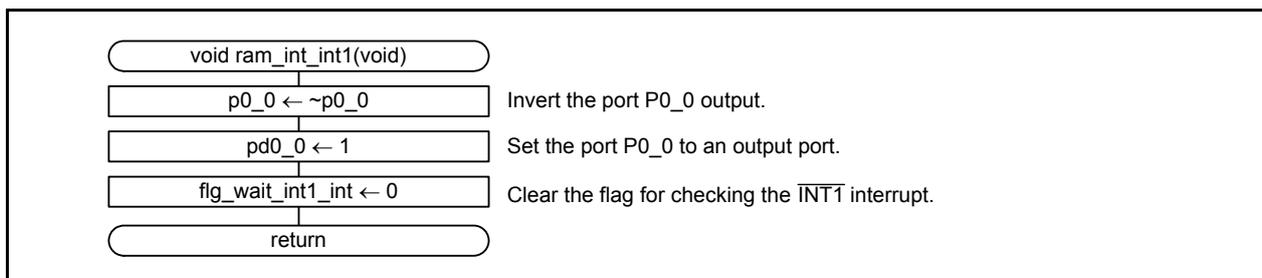
4.4.8 Renewal of RAM Vector Table Function



4.4.9 RAM Transfer Function



4.4.10 RAM $\overline{\text{INT1}}$ Interrupt Function



5. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

6. Reference Documents

M16C/63 Group User's Manual: Hardware Rev. 2.00

The latest version can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

C Compiler Manual

M16C Series/R8C Series C Compiler Package V.5.45

C Compiler User's Manual Rev. 2.00

The latest version can be downloaded from the Renesas Electronics website.

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Revision History	M16C/63 Group Power Control: Low Current Consumption Setting
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Rev.	Date	Description	
		Page	Summary
1.00	Aug. 31, 2010	—	First edition issued
1.01	Oct 29, 2010	3	Figure3.1 Stop and Restart of the Flash Memory is modified
		4	Figure3.2 Setting and Canceling Slow Read Mode is modified
		5	Figure3.3 Setting and Canceling Low Current Consumption Read Mode is modified
1.02	Dec. 28, 2011	—	Modified the program specifications.
		—	Slow Read/Wait function: Deleted.
		—	Flash memory stop/operate function: Added and placed where the slow read/wait function used to be placed.
		2	3.1.2 Wait Mode: Changed some part of the descriptions.
		2	3.1.3 Stop Mode: Modified the first sentence.
		3	Figure 3.1 Stopping and Restarting the Flash Memory: Deleted note 4.
		4	3.2.2.1 Slow Read Mode: Added the second sentence and the sentence below Figure 3.2.
		4	Figure 3.2 Setting and Canceling Slow Read Mode: Added the description regarding 1 wait to the first process, and deleted the last process, "Restore the CPU clock" from the canceling procedure.
		5	3.2.2.2 Low Current Consumption Read Mode: Rewrote the descriptions.
		5	Figure 3.3 Setting and Canceling Low Current Consumption Read Mode: Deleted the last process, "Restore the CPU clock" from the canceling procedure.
		7	4.1 Settings in the Sample Code: Changed including Table 4.1.
		8	4.2 Sample Code Operation: Changed including Figure 4.1.
		9	4.3 Function Tables: •void mcu_init(void): Changed the Outline. •void peripheral_init(void): Changed the Outline and Function. •void ram_int_int1(void): Changed.
12	4.4.1 Main Processing: Changed the explanation for peripheral_init().		
17	4.4.10 RAM INT1 Interrupt Function: Added the last process, "flg_wait_int1_int ← 0".		

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1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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